

Multilayer Power Inductor

CIG10F Series (1608/ EIA 0603)

APPLICATION

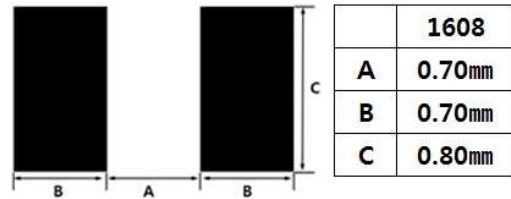
Mobile DSC, DVC, PDA etc. for DC-DC Converter



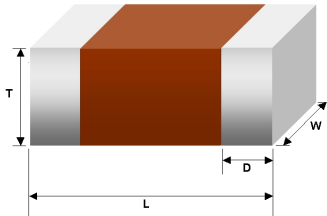
FEATURES

- The smallest multilayer power inductor (1.6mm×0.8mm)
- Much lower Profile than any other series (0.5mm max)
- Low DC resistance
- Magnetically shielded structure
- Free of all RoHS-regulated substances
- Monolithic structure for high reliability

RECOMMENDED LAND PATTERN



DIMENSION



TYPE	Dimension [mm]			
	L	W	T	D
10	1.6±0.15	0.8±0.15	0.5 max.	0.3±0.2

DESCRIPTION

Part no.	Size (inch/mm)	Inductance (uH)@1MHz	DC Resistance(Ω)	Rated Current (A) Max.
CIG10FR47MNC	0603/1608	0.47±20%	0.20±30 %	0.80
CIG10F1R0MNC	0603/1608	1.0±20%	0.30±30 %	0.70
CIG10F1R5MNC	0603/1608	1.5±20%	0.35±30 %	0.60
CIG10F2R2MNC	0603/1608	2.2±20%	0.45±30 %	0.50

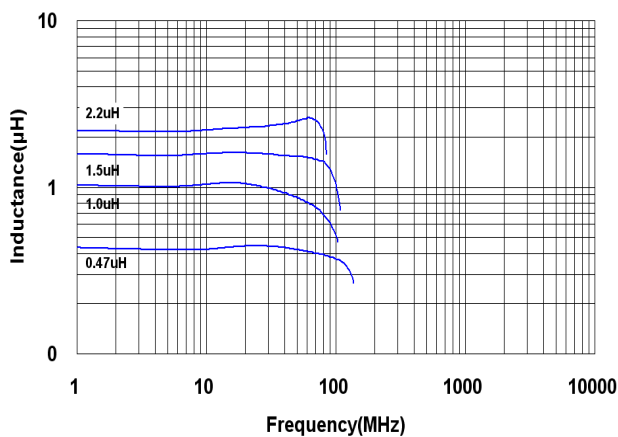
※Rated Current: DC current value when the self-generation of heat rises to 40℃ (Reference ambient temperature:25℃)

※Operating temperature range: -40 to +125℃ (Including self-temperature rise)

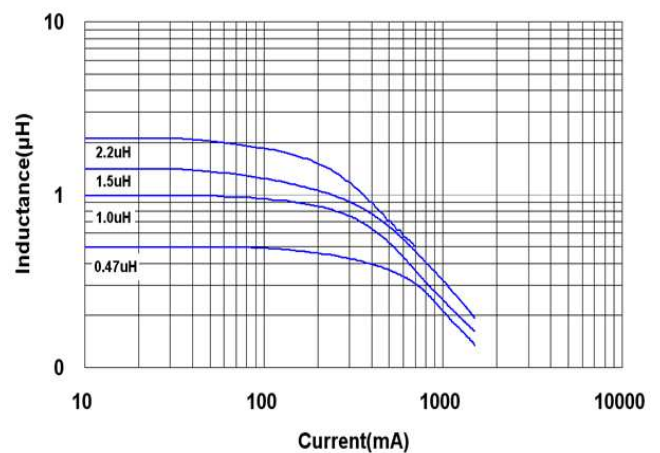
※Test equipment: Agilent :E4991A+16092A

CHARACTERISTIC DATA

1) Frequency characteristics (Typ.)



2) DC Bias characteristics (Typ.)



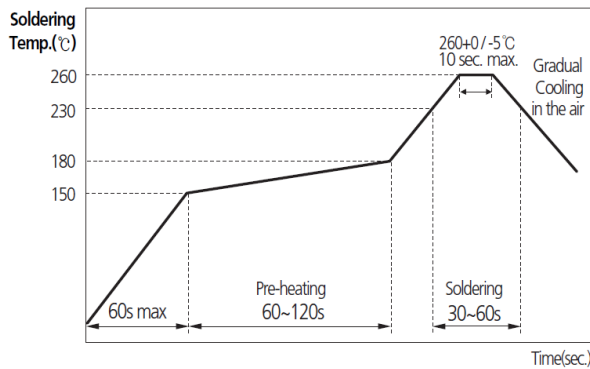
PRODUCT IDENTIFICATION

CI G 10 F 2R2 M N C
(1) (2) (3) (4) (5) (6) (7) (8)

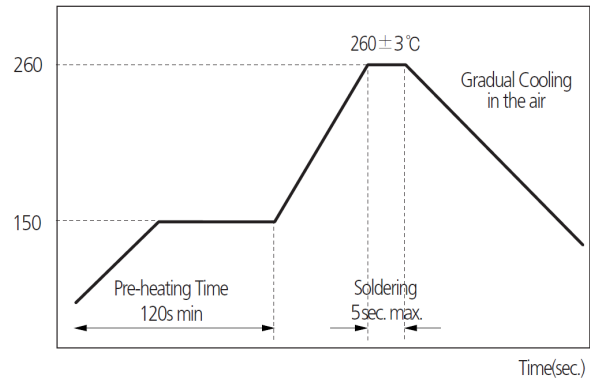
- (1) Chip Inductor
- (2) Power Inductor
- (3) Dimension
- (4) Product Series (F:Low Profile Type)
- (5) Inductance (R47:0.47uH, 2R2:2.2uH)
- (6) Tolerance (M:±20%)
- (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (8) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	4,000

Any data in this sheet are subject to change, modify or discontinue without notice. The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.